REGISTRATION FORM



FRAUNHOFER INSTITUTE FOR MICROELECTRONIC CIRCUITS AND SYSTEMS IMS

November 18th and 19th, 2014

FRAUNHOFER IMS WORKSHOP **HIGH TEMPERATURE ELECTRONICS**



Workshop Fee

• 450€ (Registration before October 17th, 2014)

• 550€ (Registration before November 7th, 2014) The workshop fee includes lunches on both days and dinner on November 18th, 2014. All participants will receive an USB memory stick with all presentations.

Cancellations

Half of the payment will be reimbursed for cancellations received before November 7th, 2014. Later cancellations will not be reimbursed!

Terms of Payment

After reception of the registration form, an invoice will be sent to the participants and the fee has to be transferred under reference of the invoice number until November 14th, 2014, at the latest. Payment by credit card is not possible.

Contact at Fraunhofer IMS: Susanne Kittner Phone +49 203 / 3783-170 Fax +49 203 / 3783-153 susanne.kittner@ims.fraunhofer.de www.ims.fraunhofer.de

Location: Fraunhofer-inHaus-Center Forsthausweg 1 47057 Duisburg Phone +49 203 / 713967-0 www.inhaus.fraunhofer.de

How to find us

http://www.inhaus.fraunhofer.de/en/about-us/Directions.html Parking opportunities can be found on the nearby university car park in Carl-Benz-Strasse.

Name / First Name / Title Affiliation Address Phone / Fax E-Mail

Signature

Please send this completed registration form: either as scan to susanne.kittner@ims.fraunhofer.de or by fax to +49 203 3783-153 until November 7th, 2014, at the latest.

Hotel Booking

Hotel rooms have been reserved at the Plaza Hotel. Please contact the hotel directly. www.hotel-plaza.de | info@hotel-plaza.de

WEDNESDAY NOVEMBER 19th, 2014

Objectives and Scope

High temperature electronics is a continuously growing market in constant need of new technologies and concepts. Fraunhofer IMS hosts a workshop on HT electronics to provide a forum for industry and academia in this field. Follow interesting presentations on applications, circuit and system design, technologies and materials for HT applications and get in touch with users and technology providers.

Workshop Venue

The workshop will be held at the Fraunhofer-inHaus-Center in Duisburg, which is located near the Fraunhofer IMS.

Organizing Committee

Holger Kappert, Prof. Dr. Rainer Kokozinski, Dr. Uwe Paschen Assistance: Sigrid van Kempen and Susanne Kittner

Miscellaneous

During the breaks there will be tabletop exhibits.

Furthermore you will have the opportunity to participate in a guided tour through the Fraunhofer IMS wafer fab as well as the labs of the inHaus-Center at the end of each day. A dinner will take place in the evening of November 18th, 2014. Further information will be given during the workshop.

	10:00	Welcome Prof. Dr. Anton Grabmaier, Fraunhofer IMS
APPLICATIONS	10:15	Highly Reliable Electronics for Harsh Environments:
		Requirements and Application in the Oil & Gas Industry
		Dr. Rüdiger Hild, Baker Hughes INTEQ GmbH
	10:45	High Temperature Sensor Conditioning and Processing
		in Aerospace Applications
		Steve Riches, GE Aviation Systems, Newmarket
SENSORS	11:15	High Temperature Hall Sensors
		Magnus Alsered, Asensor Technology AB
	12:00	Lunch
	13:00	Development of Pressure Sensors for High Temperature
		Applications
		Dr. Ronald Eberl, Siegert Thinfilm Technology GmbH
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SEMICONDUCTORS	13:30	Designing for Harsh Environment
		Ramesh Khanna, Texas Instruments
	14:00	High Temperature Semiconductors for Power
		Conversion Applications
		Pierre Delatte, Cissoid
	14:30	Break
	15:00	Further Needs in High-Temperature Power Driving
		Applications: Closing the Loop
		Gonzalo Picun, X-REL Semiconductor
	15:30	High Temperature Silicon Carbide Junction Transistors
		and Rectifiers
		Ranbir Singh, GeneSiC Semiconductor Inc.
	16:00	GaN Semiconductors at Elevated Temperatures
		Dr. Rüdiger Quay, Fraunhofer IAF

SE	9:00	The Positive Effects of Integration on High
M		Temperature Electronics
		Shane Rose, Quartzdyne, Inc.
DO	9:30	High Temperature SOI CMOS Technology Platform
Ē		for Applications up to 250°C
ORS		Holger Kappert, Fraunhofer IMS François Ayel, CEA Leti
	10:15	Break
Pb	11:00	High Temperature LTCC Magnetic Transformers
SS		and Inductors
IVE		James Galipeau, NASCENTechnology Manufacturing Inc.
S	11:30	Setting New Benchmarks: Attributes of High
		Temperature Oscillators for Clock Generation
		and Temperature Sensing
		Kouros Sariri, Frequency Management International Inc.
<u>0</u>	12:00	The Challenges of Designing Non-Ceramic
RC		Packaging for 225°C
L L		Piers Tremlett, Microsemi
BO	12:30	Lunch
ARI	13:30	Robust Electronics Based on High Temperature
S		Organic Circuit Boards I
х Р		Christiane Frueh, Robert Bosch GmbH
ACI	14:00	Robust Electronics Based on High Temperature
KAC		Organic Circuit Boards II
Z		Markus Ochs, Continental Automotive GmbH
۵	14:30	High Temperature Flex PCBs
		Koen Hollevoet, Rogers BVBA
••••	15:00	Visit of IMS wafer fab and inHaus-Center

- 16:30 Visit of IMS wafer fab and inHaus-Center
- Transfer to dinner starting from inHaus-Center 18:00